Structure of image sensor module and a method for manufacturing of wafer level package

ABSTRACT OF THE INVENTION

The present invention discloses an image sensor module and forming method of wafer level package. The image sensor module comprises a metal alloy base, a wafer level package, a lens holder, and flexible printed circuits (F.P.C.). The wafer level package having a plurality of image sensor dice and a plurality of solder balls is attached to the metal alloy base. A plurality of lens are placed in the lens holder, and the lens holder is located on the image sensor dice. The lens holder is placed in the flexible printed circuits (F.P.C.), and the flexible printed circuits (F.P.C.) has a plurality of solder joints coupled to the solder balls for conveniently transmitting signal of the image sensor dice. Moreover, the image sensor dice may be packaged with passive components or other dice with a side by side structure or a stacking structure.

Fig. 1